

Chemical content 74LVCH2T45GM

Type number	Package	Package description	Total product weight
74LVCH2T45GM	SOT902-2	XQFN8(U)	3.41389 mg

12NC	Effective	Version	Pb-free soldering			Pb soldering			Number of processing cycles	Assembly site	RHF-indicator
			MSL	PPT	MPPT	MSL	PPT	MPPT			
9352 860 59125	2018-11-09	8	1	260	30 s	1	240	20 s	3	Bangkok, Thailand	

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product
Adhesive	Additive	Non hazardous	Proprietary	0.01000	5.00000	0.29292
	Filler	Aluminium Trioxide (Al2O3)	1344-28-1	0.08000	40.00000	2.34337
	Polymer	Bisphenol-A Bisphenol-A Diglycidyl Ether copolymer	25036-25-3	0.03000	15.00000	0.87876
		Bisphenol-A/Epichlorohydrin Epoxy resin (generic)	25068-38-6	0.02000	10.00000	0.58584
		Resin system	Proprietary	0.06000	30.00000	1.75753
		subTotal		0.20000	100.00000	5.85842
Die	Doped silicon	Silicon (Si)	7440-21-3	0.12058	100.00000	3.53197
		subTotal		0.12058	100.00000	3.53197
Lead Frame Material	Copper alloy	Copper (Cu)	7440-50-8	1.55200	97.00000	45.46134
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.04800	3.00000	1.40602
		subTotal		1.60000	100.00000	46.86736
Mould Compound	Additive	Non hazardous	Proprietary	0.04438	3.17000	1.29998
	Filler	Silica fused	60676-86-0	1.18272	84.48000	34.64435
	Flame retardant	Magnesium Hydroxide (Mg(OH)2)	1309-42-8	0.04998	3.57000	1.46402
	Pigment	Carbon black	1333-86-4	0.00252	0.18000	0.07382
	Polymer	1,4-bis(methoxymethyl)benzene/phenol copolymer	26834-02-6	0.04900	3.50000	1.43531
		Epoxy resin system	Proprietary	0.04998	3.57000	1.46402
		Tetramethylbiphenyl diglycidyl ether	85954-11-6	0.02142	1.53000	0.62744
		subTotal		1.40000	100.00000	41.00894
Pre-plating	Pure metal layer	Gold (Au)	7440-57-5	0.00050	1.00000	0.01465
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.04850	97.00000	1.42067
		Palladium (Pd)	7440-05-3	0.00100	2.00000	0.02929
		subTotal		0.05000	100.00000	1.46461
Wire	Pure metal	Gold (Au)	7440-57-5	0.04288	99.00000	1.25616
		Palladium (Pd)	7440-05-3	0.00043	1.00000	0.01269
		subTotal		0.04332	100.00000	1.26885

Note(s):

1) This is a generic description of the substance used as the actual composition of the substances are either considered proprietary or no official CAS number is available. If a CAS number is given, it is the closest match available.

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